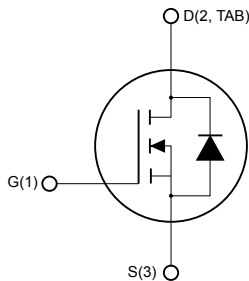
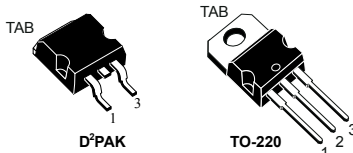


## Automotive N-channel 55 V, 6.5 mΩ typ., 80 A STripFET II Power MOSFETs in D<sup>2</sup>PAK and TO-220 packages



NG1D2TS3



### Features

Order codes	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STB141NF55	55 V	< 8 mΩ	80 A
STP141NF55			



- AEC-Q101 qualified
- Exceptional dv/dt capability
- 100% avalanche tested
- Low gate charge

### Applications

- Switching applications

### Description

These Power MOSFETs have been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the devices suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.

#### Product status links

[STB141NF55](#)
[STP141NF55](#)

#### Product summary

Order code	STB141NF55
Marking	B141NF55
Package	D <sup>2</sup> PAK
Packing	Tape and reel
Order code	STP141NF55
Marking	P141NF55
Package	TO-220
Packing	Tube

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	55	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	80	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	80	A
$I_{DM}^{(2)}$	Drain current (pulsed)	320	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	300	W
	Derating factor	2	W/°C
$dv/dt^{(3)}$	Peak diode recovery voltage slope	10	V/ns
$E_{AS}^{(4)}$	Single pulse avalanche energy	1.3	J
$T_{stg}$	Storage temperature range	-55 to 175	°C
$T_j$	Operating junction temperature range		

1. Current limited by package.
2. Pulse width limited by safe operating area.
3.  $I_{SD} \leq 80\text{ A}$ ,  $di/dt \leq 300\text{ A}/\mu\text{s}$ ,  $V_{DD} = 80\% V_{(BR)DSS}$
4. Starting  $T_j = 25\text{ }^\circ\text{C}$ ,  $I_D = 40\text{ A}$ ,  $V_{DD} = 30\text{ V}$

**Table 2. Thermal data**

Symbol	Parameter	Value		Unit
		TO -220	D <sup>2</sup> PAK	
$R_{thj-case}$	Thermal resistance junction-case max	0.5		°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.5	-	°C/W
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb max	-	35	°C/W
$T_l$	Maximum lead temperature for soldering purpose (for 10 sec, 1.6 mm from case)	300		°C

1. When mounted on 1 inch<sup>2</sup>, FR4 board, 2 oz Cu

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 3. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\ \mu\text{A}$ , $V_{GS} = 0\ \text{V}$	55			V
$I_{DSS}$	Zero gate voltage drain ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$			1	$\mu\text{A}$
		$V_{DS} = \text{Max rating}$ , $T_C = 125\text{ °C}$			10	
$I_{GSS}$	Gate-body leakage ( $V_{DS} = 0$ )	$V_{GS} = \pm 20\ \text{V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\ \text{V}$ , $I_D = 40\ \text{A}$		6.5	8	m $\Omega$

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} = 15\ \text{V}$ , $I_D = 40\ \text{A}$	-	100	-	S
$C_{iss}$	Input capacitance	$V_{DS} = 25\ \text{V}$ , $f = 1\ \text{MHz}$ $V_{GS} = 0$	-	5300	-	$\mu\text{F}$
$C_{oss}$	Output capacitance		-	1000	-	
$C_{rss}$	Reverse transfer capacitance		-	290	-	
$Q_g$	Total gate charge	$V_{DD} = 44\ \text{V}$ , $I_D = 80\ \text{A}$	-	142	-	nC
$Q_{gs}$	Gate-source charge	$V_{GS} = 10\ \text{V}$	-	27	-	
$Q_{gd}$	Gate-drain charge	(see Figure 14. Test circuit for gate charge behavior)	-	55	-	

1. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

**Table 5. Switching times**

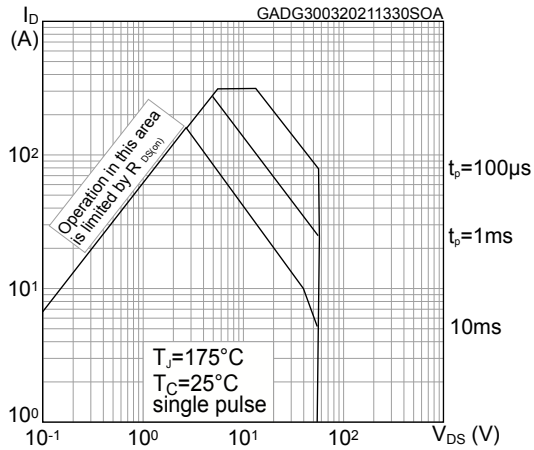
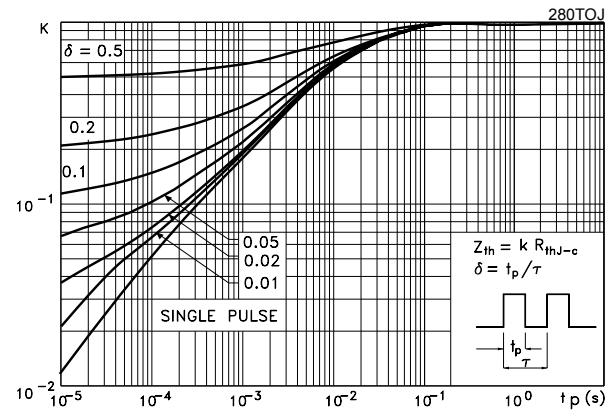
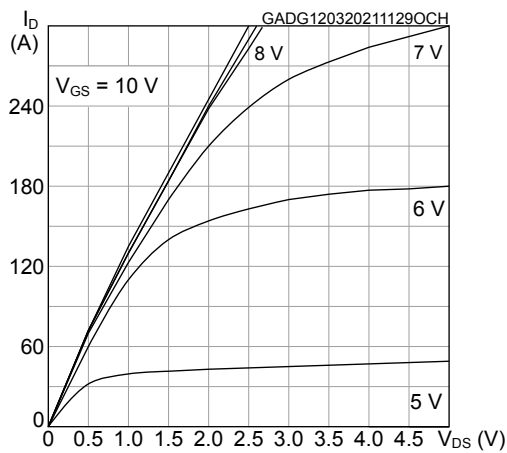
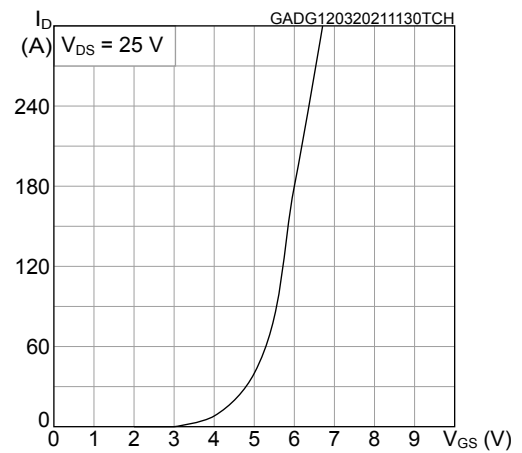
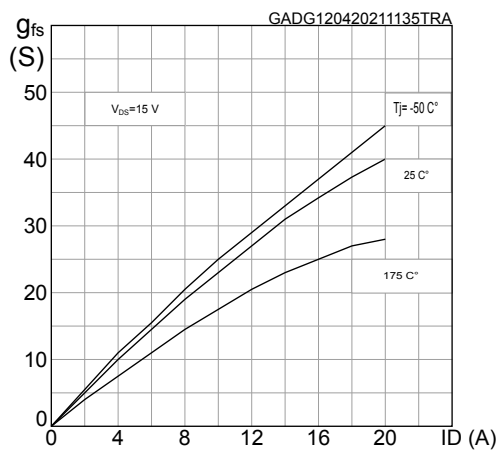
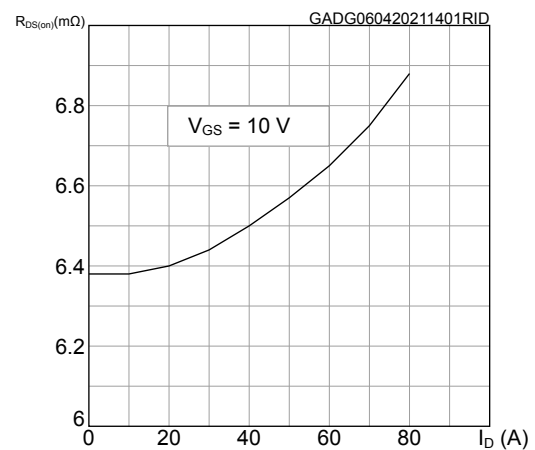
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 27.5\ \text{V}$ , $I_D = 40\ \text{A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\ \text{V}$	-	30	-	ns
$t_r$	Rise time		-	150	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Test circuit for resistive load switching times)	-	125	-	ns
$t_f$	Fall time		-	45	-	ns

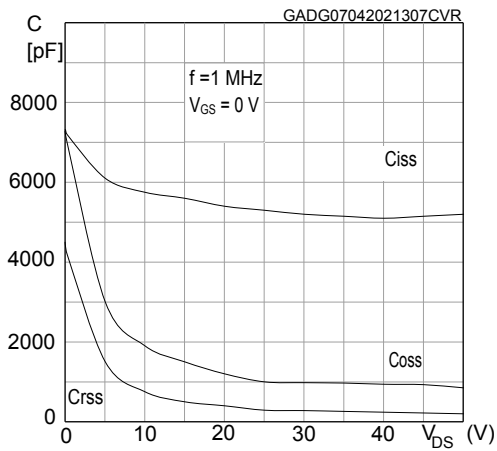
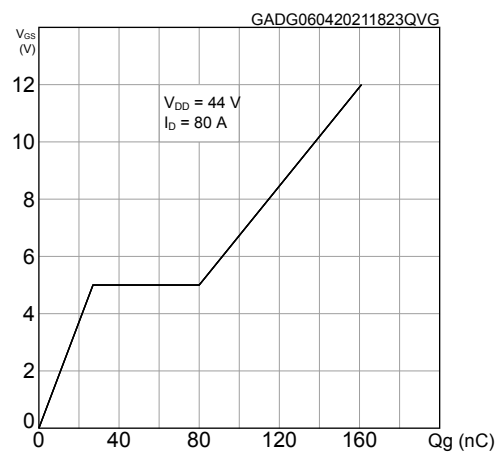
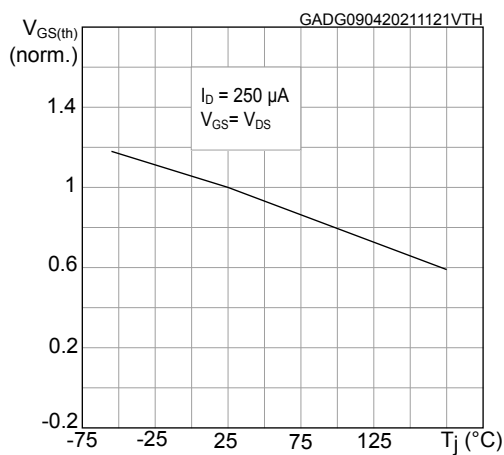
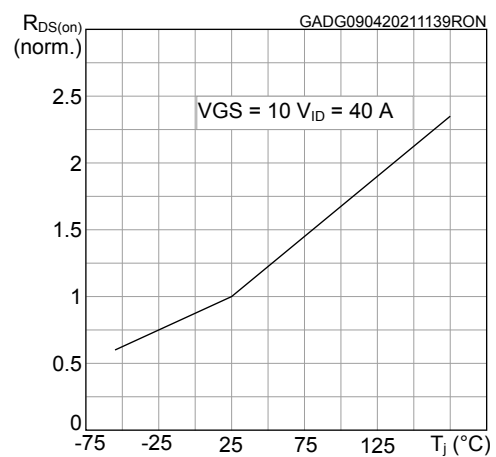
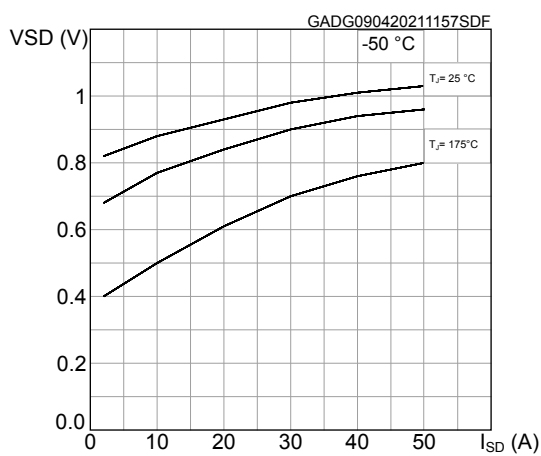
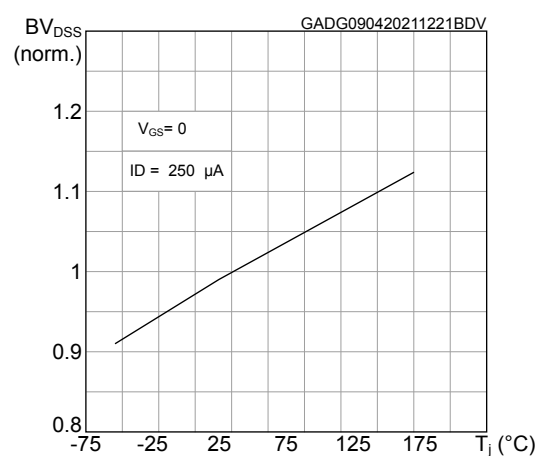
**Table 6. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		180	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		320	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 80 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 80 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	-	90		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 20 \text{ V}, T_J = 150 \text{ }^\circ\text{C}$	-	275		nC
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	6.5		A

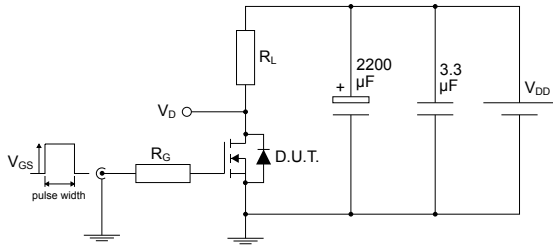
1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration=300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

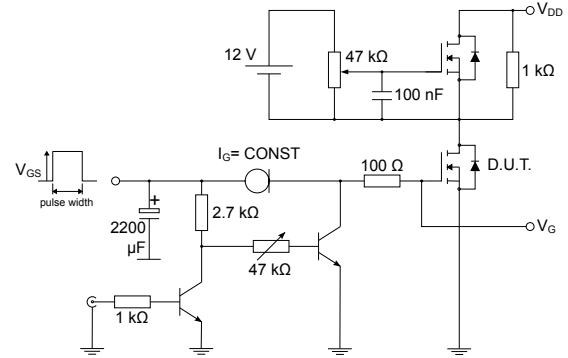
**Figure 1. Safe operating area**

**Figure 2. Thermal impedance**

**Figure 3. Output characteristics**

**Figure 4. Transfer characteristics**

**Figure 5. Transconductance**

**Figure 6. Static drain-source on resistance**


**Figure 7. Capacitance variations**

**Figure 8. Gate charge vs gate-source voltage**

**Figure 9. Normalized breakdown voltage vs temperature**

**Figure 10. Normalized on resistance vs temperature**

**Figure 11. Source-drain diode forward characteristics**

**Figure 12. Normalized  $BV_{DSS}$  vs temperature**


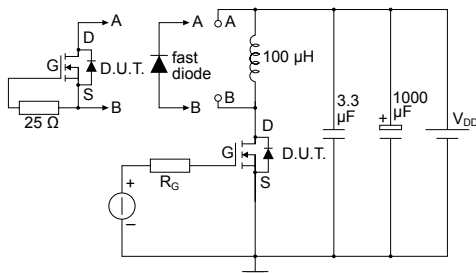
### 3 Test circuits

**Figure 13. Test circuit for resistive load switching times**


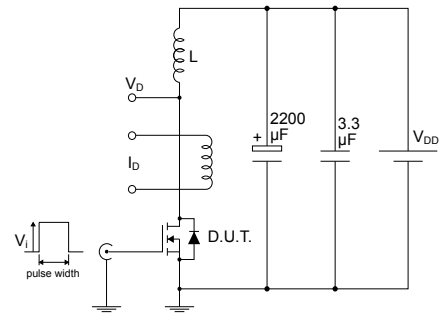
AM01468v1

**Figure 14. Test circuit for gate charge behavior**


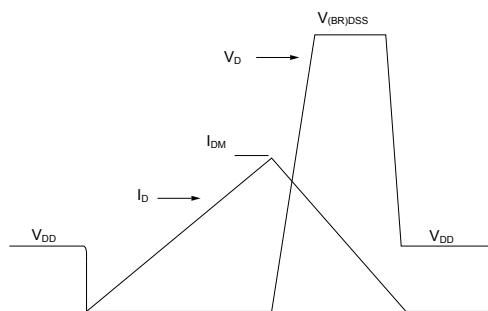
AM01469v1

**Figure 15. Test circuit for inductive load switching and diode recovery times**


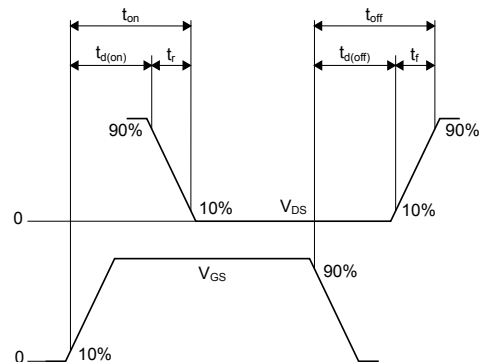
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**Figure 16. Unclamped inductive load test circuit**


AM01471v1

**Figure 17. Unclamped inductive waveform**


AM01472v1

**Figure 18. Switching time waveform**


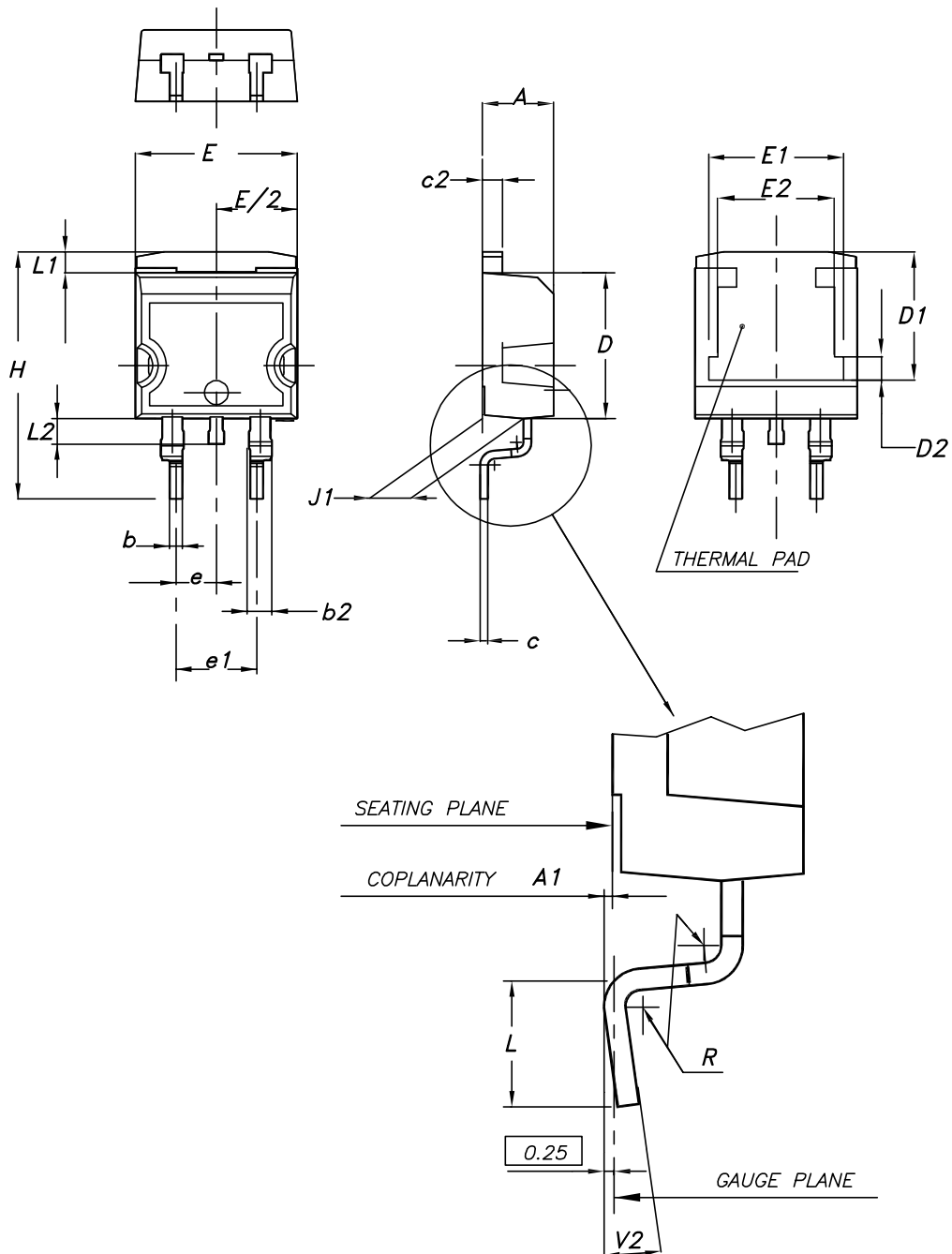
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## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 D<sup>2</sup>PAK (TO-263) type A package information

Figure 19. D<sup>2</sup>PAK (TO-263) type A package outline



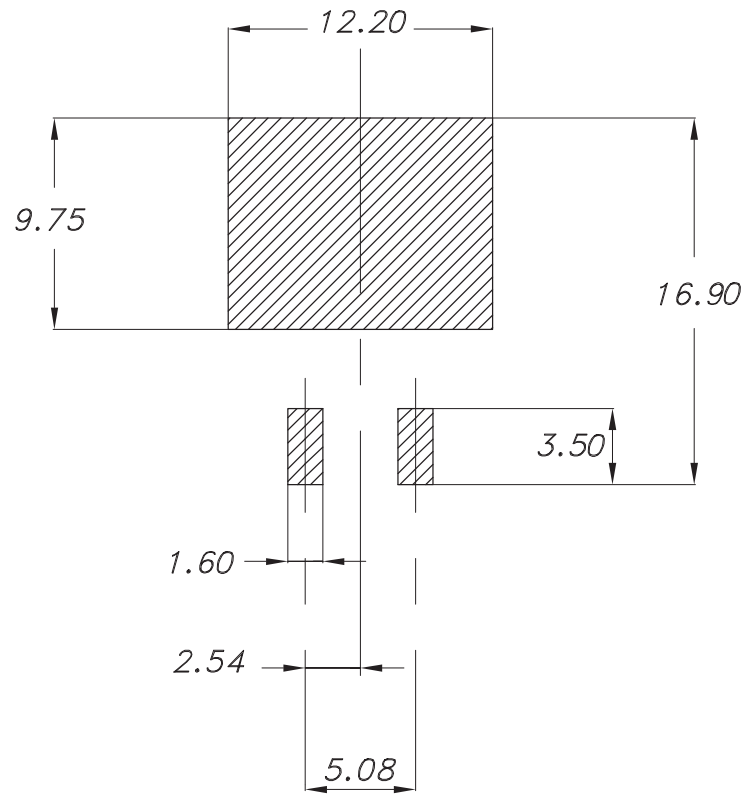
0079457\_26



**Table 7. D<sup>2</sup>PAK (TO-263) type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

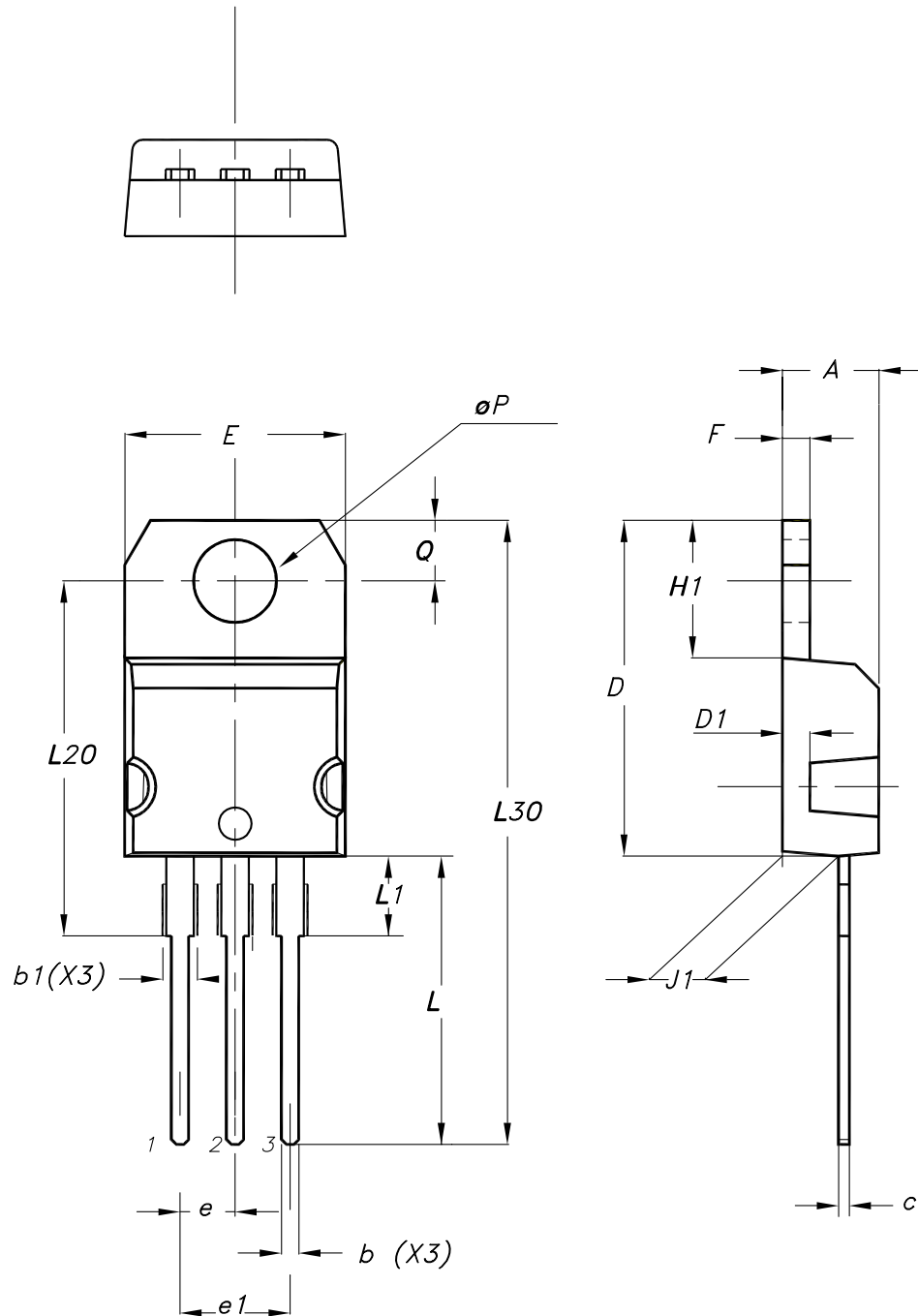
**Figure 20. D<sup>2</sup>PAK (TO-263) recommended footprint (dimensions are in mm)**



0079457\_Rev26\_footprint

## 4.2 TO-220 type A package information

Figure 21. TO-220 type A package outline



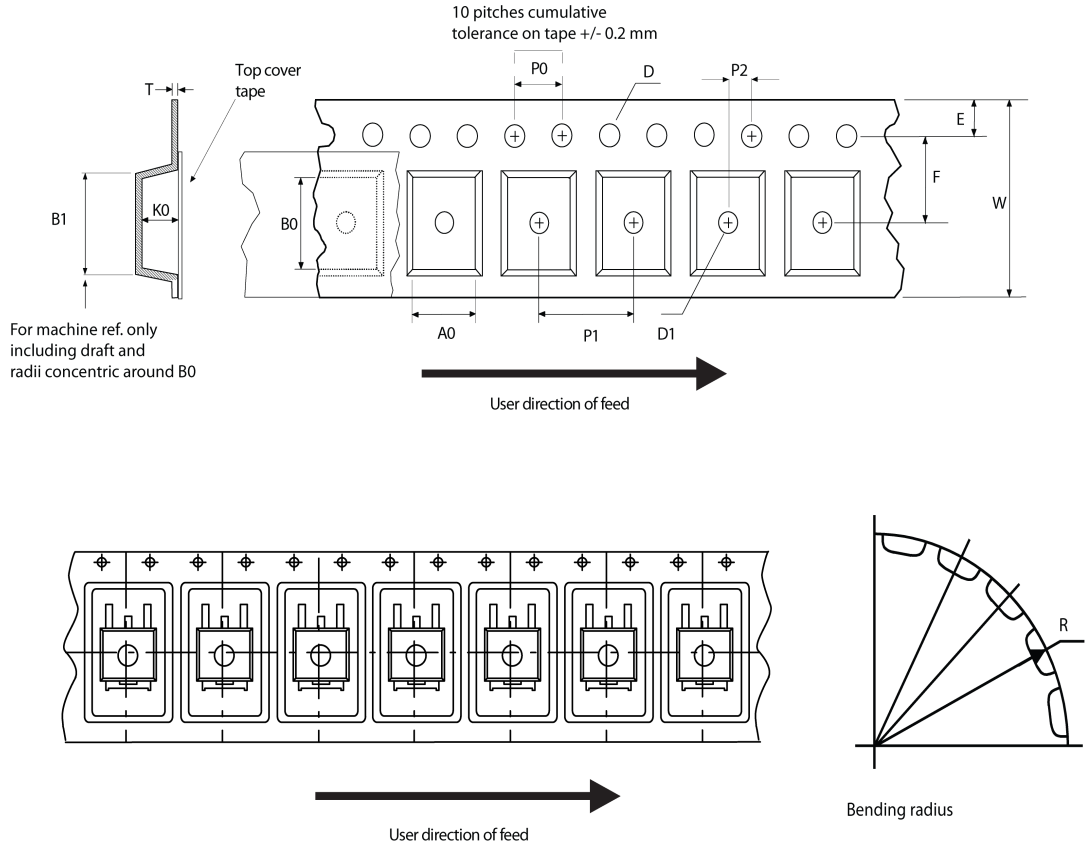
0015988\_typeA\_Rev\_23

**Table 8. TO-220 type A package mechanical data**

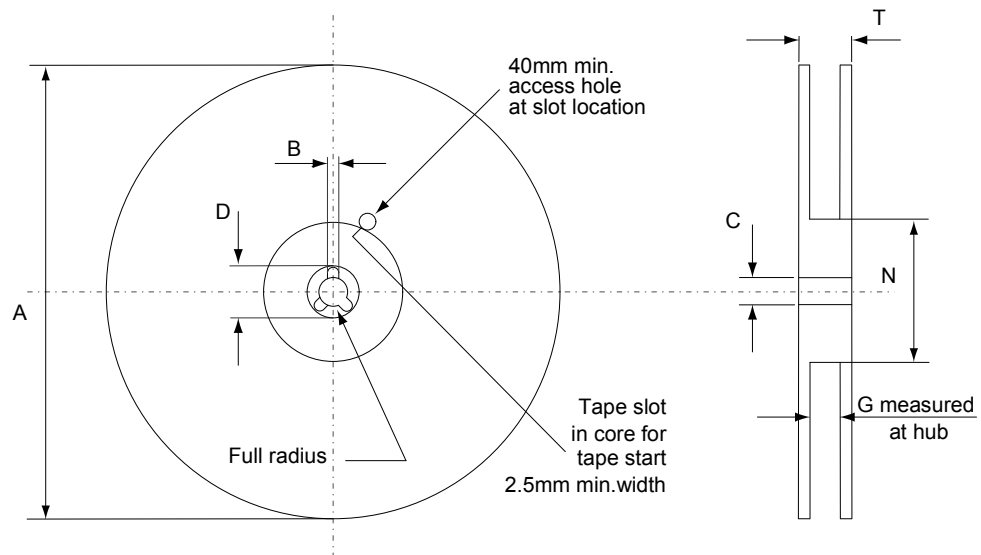
Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

### 4.3 D<sup>2</sup>PAK packing information

Figure 22. D<sup>2</sup>PAK tape outline



AM08852v1

**Figure 23. D<sup>2</sup>PAK reel outline**


AM06038v1

**Table 9. D<sup>2</sup>PAK tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## Revision history

**Table 10. Document revision history**

Date	Version	Changes
01-Aug-2007	1	First release.
03-Jan-2022	2	The part number in IPAK package has been removed.

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